



Click [here](#) for the 3D model.

### Dimensions

|           |                 |
|-----------|-----------------|
| Chip Size | 0402            |
| L         | 1mm +/-0.05mm   |
| W         | 0.5mm +/-0.05mm |
| T         | 0.5mm +/-0.05mm |
| S         | 0.3mm MIN       |
| B         | 0.3mm +/-0.1mm  |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 10000                  |

### General Information

|                  |   |
|------------------|---|
| Series           | ESD SMD Auto COG  |
| Style            | SMD Chip  |
| Description      | SMD, MLCC, Temperature Stable, Electro Static Discharge, Automotive Grade |
| Features         | Temperature Stable, Automotive Grade                                      |
| RoHS             | Yes   |
| Termination      | Tin   |
| Marking          | No  |
| Qualifications   | AEC-Q200  |
| AEC-Q200         | Yes   |
| Component Weight | 1.06 mg   |
| Shelf Life       | 78 Weeks  |
| MSL              | 1   |

### Specifications

|  |                        |
|--|------------------------|
| Capacitance  | 1000 pF                |
| Measurement Condition  | 1 MHz 1.0Vrms          |
| Capacitance Tolerance  | 1%                     |
| Voltage DC   | 25 VDC                 |
| ESD Level per AEC-Q200   | 4,000 V ESD Level      |
| Dielectric Withstanding Voltage                                    | 62.5 VDC               |
| Temperature Range  | -55/+125°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms     |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |